

V_{DSS} , 100V R_{DS(ON)} , 25mΩ (max.) @ V_{GS}=10V R_{DS(ON)} , 28mΩ (max.) @ V_{GS}=4.5V I_D , 9.8A	SOP-8	

Description	Features
<p>The SG100N03S uses advanced Trench technology and designs to provide excellent R_{DS(ON)} with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.</p>	<ul style="list-style-type: none"> • Low On-Resistance • Low Input Capacitance • Low Miller Charge • Low Input / Output Leakage • Pb-free lead plating; RoHS compliant
	Applications
	<ul style="list-style-type: none"> • Motor / Body Load Control • Automotive Systems • Load Switch • DC-DC converters and Off-line UPS

Ordering Information

Ordering Code	RoHS Status	Package	Package Code	Packing	Quantity
SG100N03S	Halogen-Free	SOP-8	S	Tape & Reel	3,000

Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	T _A =25°C	9.8
		T _A =70°C	7.9
Drain Current-Pulsed ^{Note 1}	I _{DM}	35	A
Avalanche Current, L=3mH	I _{AS}	6.5	A
Avalanche Energy, L=3mH	E _{AS}	63	mJ
Maximum Power Dissipation	P _D	T _A =25°C	3.1
		T _A =70°C	2
Storage Temperature Range	T _{STG}	-55 to +150	°C
Operating Junction Temperature Range	T _J	-55 to +150	°C

Thermal Resistance Ratings

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Maximum Junction-to-Ambient	R _{θJA}	t ≤ 10s	-	-	40	°C/W
Maximum Junction-to-Case	R _{θJC}	Steady State	-	-	25	°C/W

Electrical Characteristics (T_J=25°C unless otherwise noted)

OFF CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _{DS} =250μA	100	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA

ON CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Gate Threshold Voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _{DS} =250μA	1.2	1.8	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _{DS} =10A	-	-	25	mΩ
		V _{GS} =4.5V, I _{DS} =8A	-	-	28	

DYNAMIC CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHz	-	1325	-	pF
Output Capacitance	C _{oss}		-	110	-	
Reverse Transfer Capacitance	C _{rss}		-	64	-	

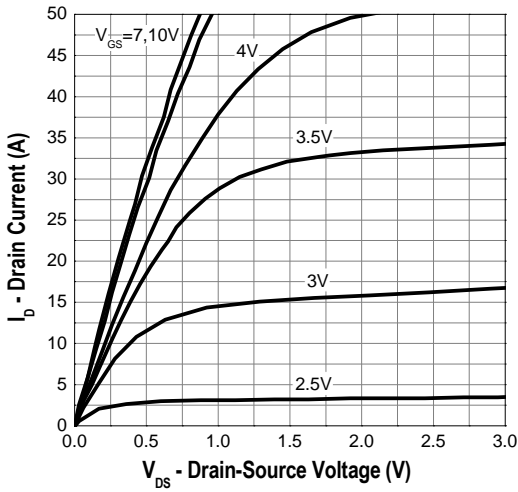
SWITCHING CHARACTERISTICS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Turn-On Delay Time	T _{d(on)}	V _{GS} =10V, V _{DS} =50V, R _L =5Ω, R _{GEN} =3Ω	-	7	-	ns
Rise Time	t _r		-	7	-	
Turn-Off Delay Time	T _{d(off)}		-	29	-	
Fall Time	t _f		-	7	-	
Total Gate Charge at 10V	Q _g	V _{GS} =10V, V _{DS} =50V, I _D =10A	-	34	-	nC
Gate to Source Gate Charge	Q _{gs}		-	6	-	
Gate to Drain "Miller" Charge	Q _{gd}		-	9	-	

DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =10A	-	-	1.3	V
Body Diode Reverse Recovery Time	t _{rr}	I _F =10A, di/dt=500A/μs	-	32	-	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	200	-	nC

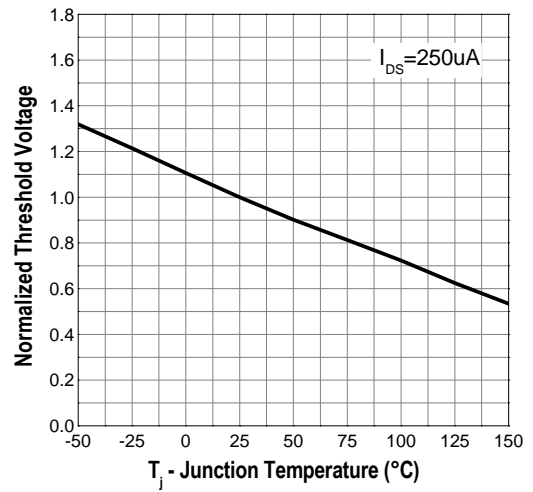
- Notes:**
- Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
 - R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design while R_{θJA} is determined by the user's board design. R_{θJA} shown below for single device operation on FR-4 in still air.

Typical Operating Characteristics

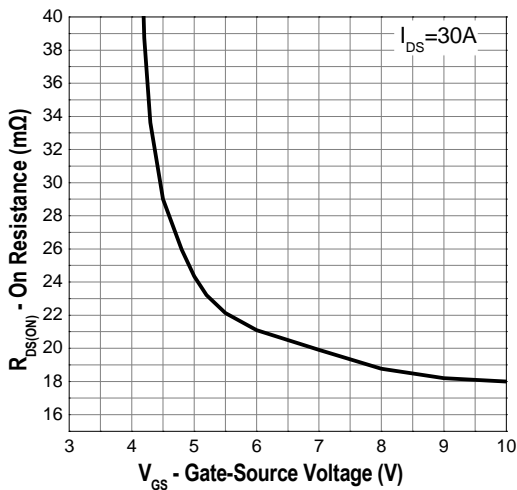
Output Characteristics



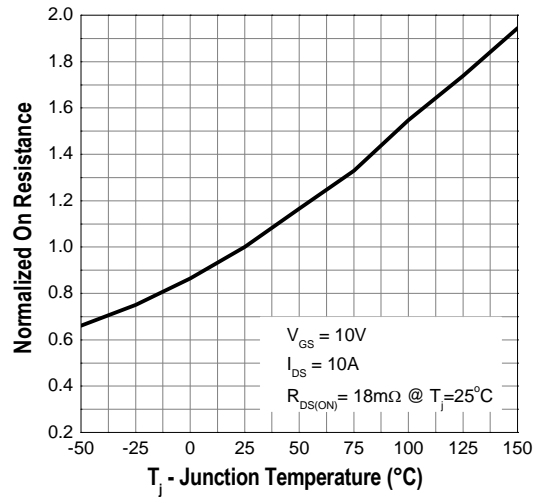
Gate Threshold Voltage



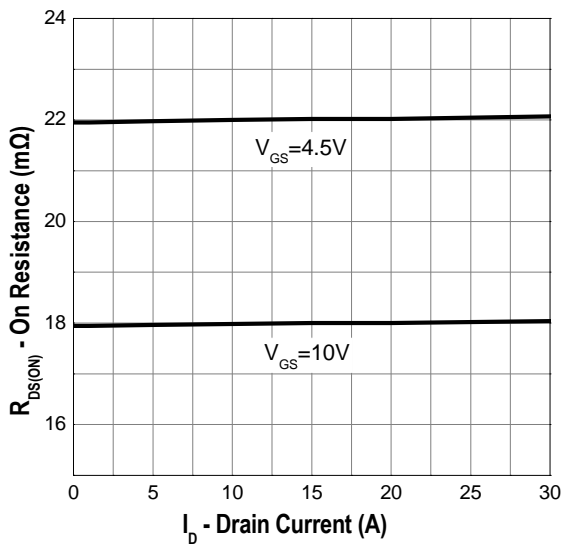
Gate-Source On Resistance



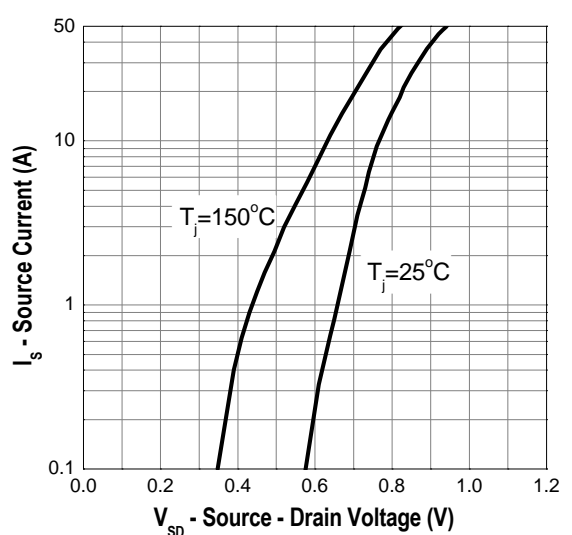
Drain-Source On Resistance



Drain-Source On Resistance

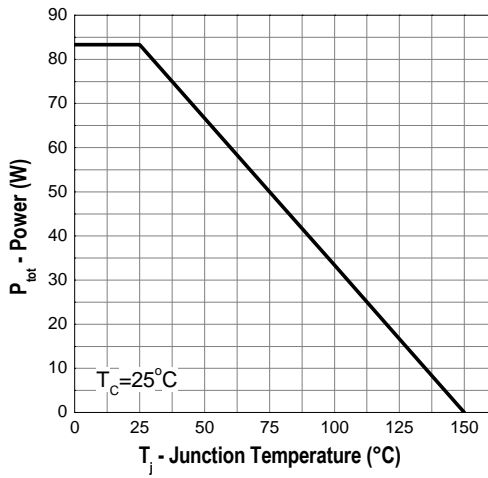


Source-Drain Diode Forward

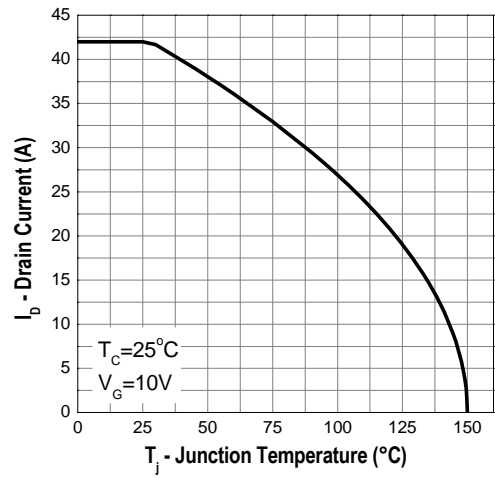


Typical Operating Characteristics (Cont.)

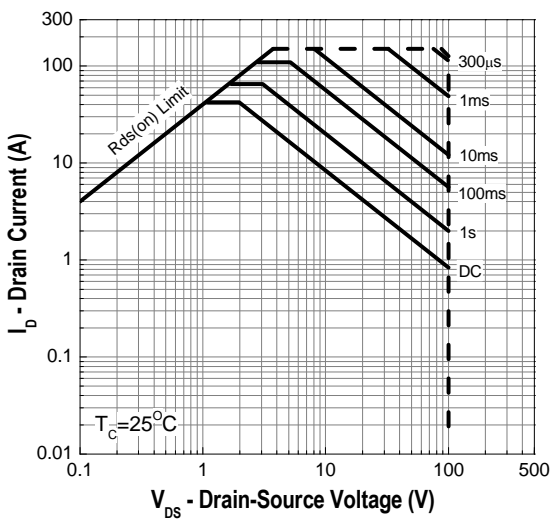
Power Dissipation



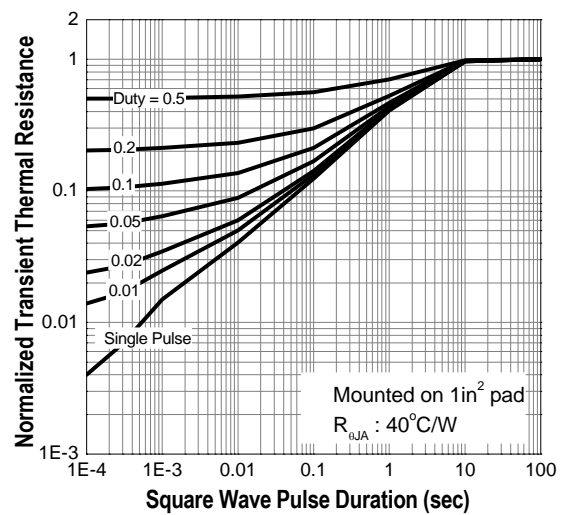
Drain Current



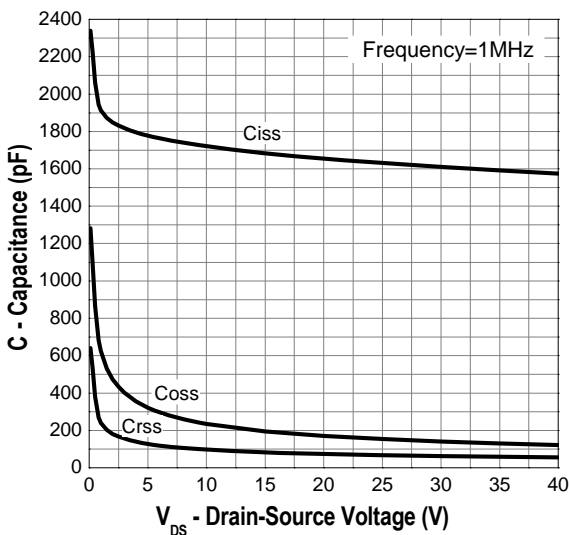
Safe Operation Area



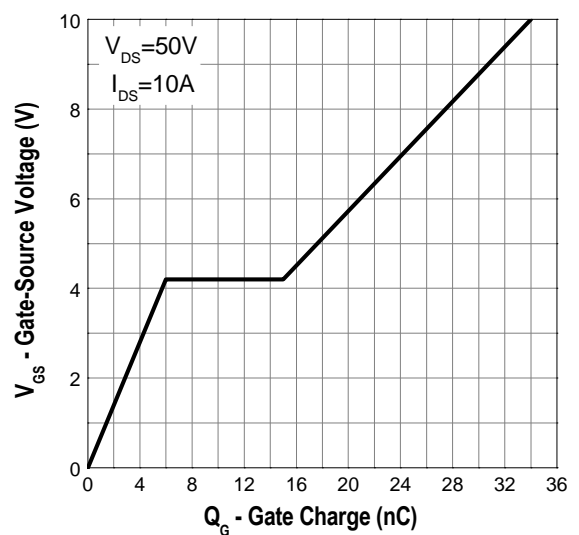
Thermal Transient Impedance



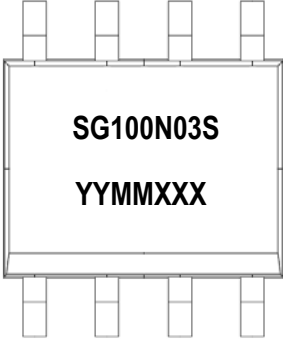
Capacitance



Gate Charge

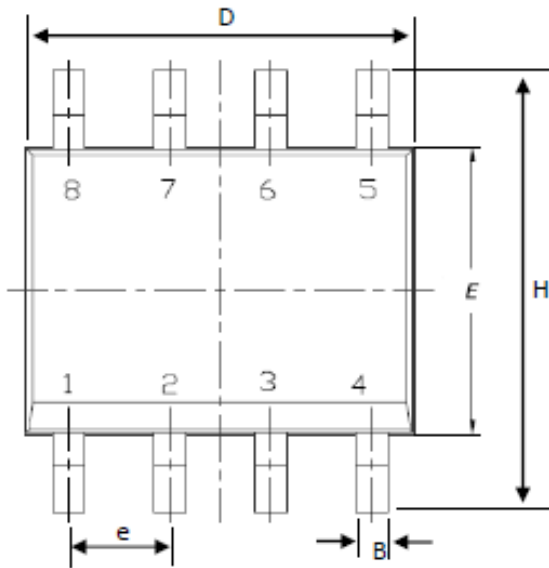


Marking Information

SOP-8 (S)	Marking Rule
<p>Laser Marking</p>  <p>Diagram</p>	<p><u>Line 1</u> : Device Name SG100N03S</p> <p><u>Line 2</u> : Date Code YYMMXXX</p> <p>YY : Year Code MM : Month Code XXX : Serial Number</p>

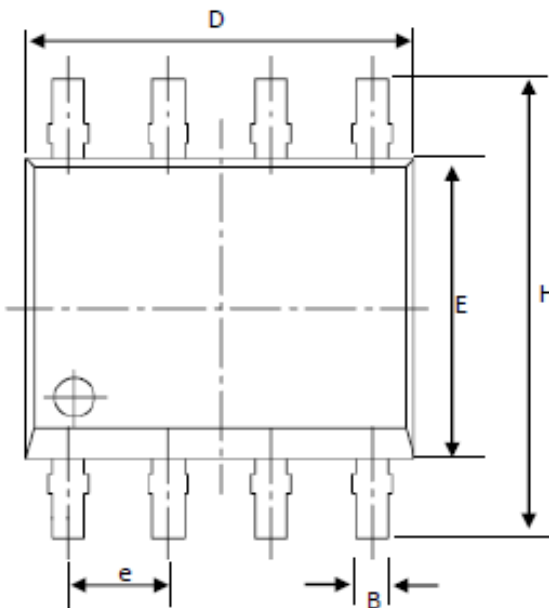
Package of Dimension

G-TYPE



Symbol	Min	Nor	Max
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
B	0.31	0.41	0.51
c	0.17	0.21	0.25
D	4.80	4.90	5.00
E	3.80	3.90	4.00
e	1.27	1.27	1.27
H	5.80	6.00	6.20
L	0.40	0.84	1.27
α	0.00	4.00	8.00

B-TYPE

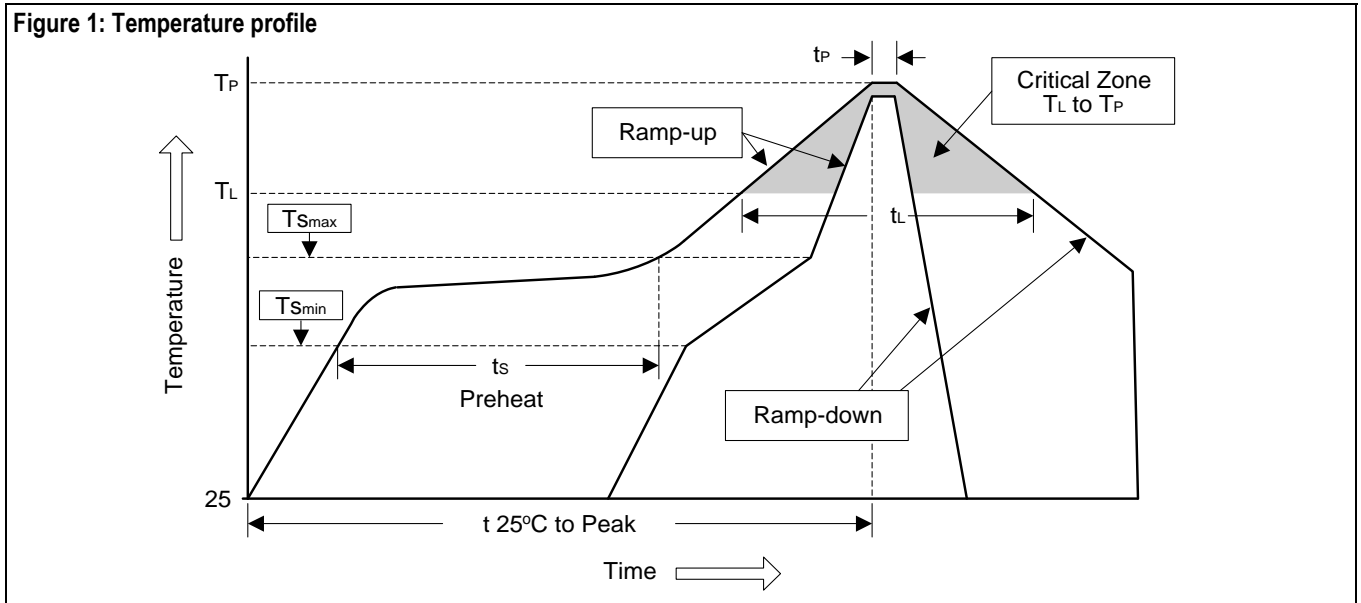


1. All dimension are in millimeters.
2. Dimension does not include burrs and mold flash/protrusions.

Soldering Methods for Silicongear's Products

1. Storage environment: Temperature=10°C to 35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices

Figure 1: Temperature profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Preheat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (min to max) (t_s)	60 to 120 sec	60 to 180 sec
T_{Smax} to T_L		
- Ramp-up Rate	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60 to 150 sec	60 to 150 sec
Peak Temperature (T_P)	240°C $\pm 0/-5^{\circ}\text{C}$	260°C $\pm 0/-5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature (t_P)	10 to 30 sec	20 to 40 sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak Temperature	Dipping Time
Pb devices.	245°C $\pm 5^{\circ}\text{C}$	5sec ± 1 sec
Pb-Free devices.	260°C $\pm 0/-5^{\circ}\text{C}$	5sec ± 1 sec

Important Notice

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